Indium Bonding

Service

Kurt J. Lesker Company

MATERIALS™ DIVISION

Applications

- Sputtering target and backing plate bonding

Features

- Highest thermally conductive bond offered
- Thorough bond coverage
- Malleable solder allows for thermal expansion during sputtering
- Provides support for fragile target materials
- Compatible with a wide range of target materials

Bonding Process

- Target bonding surface may be coated prior to bonding to improve adhesion
- Indium reflow process provides complete bond coverage
- Accurate alignment of target on backing plate
- Bonded target assemblies are cleaned and ready for use in vacuum

Options

- Wide range of sizes and shapes
- Multi-tile assemblies
- Complex backing plate configurations
- Compatible with most target materials

Specifications

Property	Value
Maximum Operating Temperature	150°C
Thermal Conductivity	83 W/m·K
Coefficient of Thermal Expansion	32.1 x 10^{-6} K^{-1}
Electrical Resistivity	8 x 10^{-6} ohm-cm
Bond Coverage	>95%
Bond Line Thickness	0.010"-0.020"
Bond Line Thickness Tolerance	± 0.003"

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